



STM32V8 series

**New generation of high-performance MCUs
for demanding industrial applications.**



New milestone in the high-performance MCU roadmap

STM32V8



**World-first MCUs built on 18 nm process technology
delivering next-level performance**

The STM32 portfolio



Five product categories



Wireless
MCU

Short- and long-range connectivity



Ultra-low-power
MCU

32-bit general-purpose microcontrollers: from 75 to 5,072 CoreMark score



Mainstream
MCU

High-performance
MCU



Embedded
MPU

32- and 64-bit microprocessors



Enabling edge AI solutions



Scalable security



STM32 portfolio

 MPU

 High-performance MCUs

 Mainstream MCUs

 Ultra-low-power MCUs

 Wireless MCUs

STM32MP1
1 GHz Cortex®-A7
209 MHz Cortex®-M4

STM32MP2
Dual 1.5 GHz Cortex®-A35
400 MHz Cortex®-M33

STM32F7
1,082 CoreMark
216 MHz Cortex®-M7

STM32N6
3,360 CoreMark
800 MHz Cortex®-M55
Neural processing unit

STM32V8
Up to 5,072 CoreMark
800 MHz Cortex®-M85

STM32F2
398 CoreMark
120 MHz Cortex®-M3

STM32F4
608 CoreMark
180 MHz Cortex®-M4

STM32H5
1,023 CoreMark
250 MHz Cortex®-M33

STM32H7
3,347 CoreMark
Up to 600 MHz Cortex®-M7
240 MHz Cortex®-M4

STM32F3
245 CoreMark
72 MHz Cortex®-M4

STM32G4
569 CoreMark
170 MHz Cortex®-M4

Mixed-signal MCUs

STM32C0
114 CoreMark
48 MHz Cortex®-M0+

STM32F0
106 CoreMark
48 MHz Cortex®-M0

STM32G0
142 CoreMark
64 MHz Cortex®-M0+

STM32F1
177 CoreMark
72 MHz Cortex®-M3

STM32L0
75 CoreMark
32 MHz Cortex®-M0+

STM32U0
140 CoreMark
56 MHz Cortex®-M0+

STM32L4
273 CoreMark
80 MHz Cortex®-M4

STM32U3
393 CoreMark
96 MHz Cortex®-M33

STM32L4+
409 CoreMark
120 MHz Cortex®-M4

STM32L5
443 CoreMark
110 MHz Cortex®-M33

STM32U5
651 CoreMark
160 MHz Cortex®-M33

STM32WL
162 CoreMark
48 MHz Cortex®-M4
48 MHz Cortex®-M0+

STM32WB0
156 CoreMark
64 MHz Cortex®-M0+

STM32WB
216 CoreMark
64 MHz Cortex®-M4
32 MHz Cortex®-M0+

STM32WBA
407 CoreMark
100 MHz Cortex®-M33





STM32V8: a new DNA for high-performance MCUs

FD-SOI and phase-change memory technology on 18 nm node



- High integration on single die
- High density: larger program embedded NVM
- Excellent power efficiency
- Strong robustness in harsh environments



Cutting-edge architecture & advanced features



- Powerful Arm Cortex®-M85 core
- Scalar & vectorial performance with Helium
- Rich features & memory integration
- Strong security for regulatory compliance
 - PSA Certified L3 & SESIP3 targets



Arm Cortex[®]-M85

significant performance increase in scalar, DSP, and ML compared with Arm Cortex[®]-M7

800 MHz frequency
thanks to 18 nm technology node

4 Mbytes of embedded NVM

140°C junction temperature

What this means for your applications



**Factory automation
& robotics**



**Energy management
systems**



**Smart cities
& buildings**

Digital signal processing &
analysis

Power conversion

Motor control

Secure IoT connectivity



**Healthcare &
biosensing**



Audio applications



**Transportation
(ebikes)**

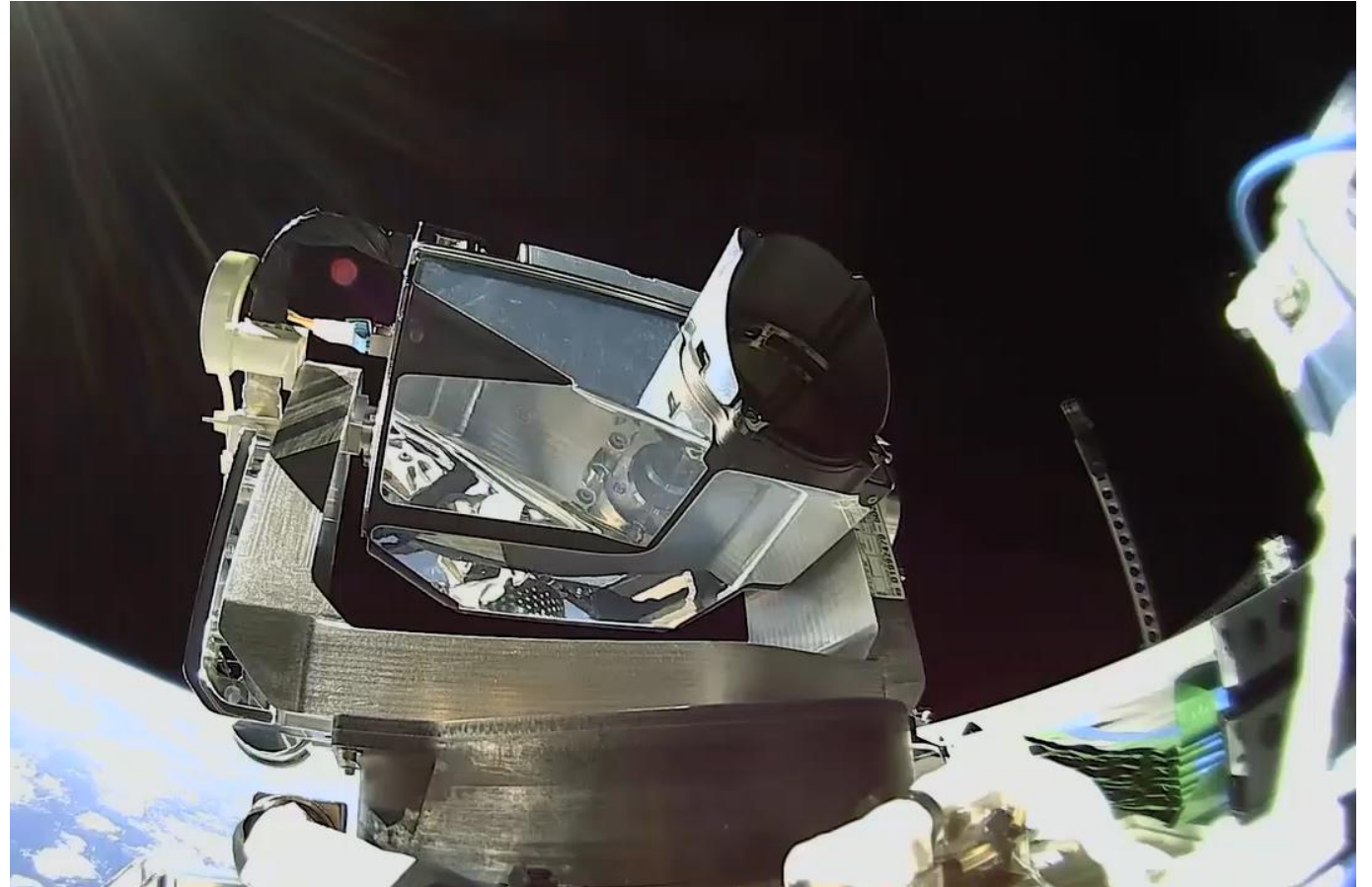


Aerospace

Aerospace application: STM32V8 in SpaceX mini-laser

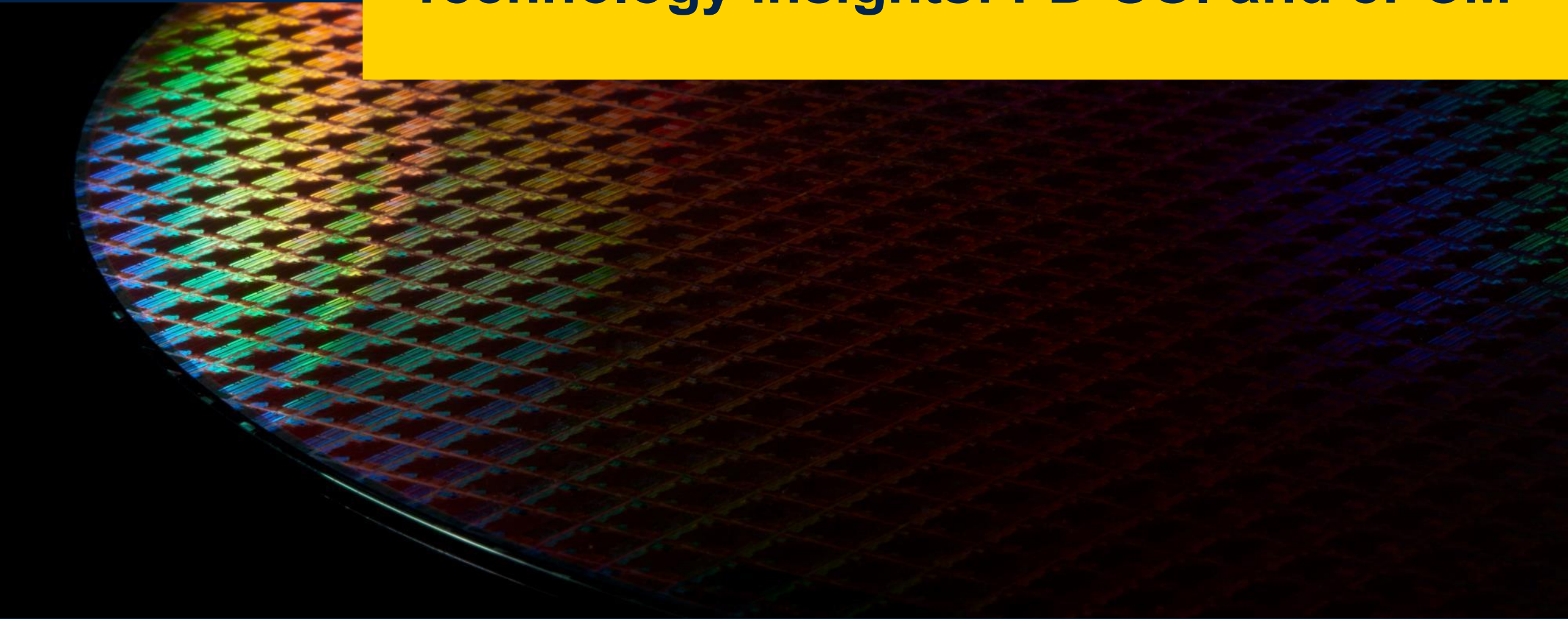
“The STM32V8’s high computing performance and integration of large embedded memory and digital features were critical in meeting our demanding real-time processing requirements, while providing a higher level of reliability and robustness to low Earth orbit environment, thanks to the 18nm FD-SOI technology.”

**Michael Nicolls, Vice President,
Starlink Engineering at SpaceX**



High-speed connectivity system in Starlink satellite network

Technology insights: FD-SOI and ePCM



The main benefits in the context of STM32V8

Competitive advantages

- Outstanding **energy efficiency** through FD-SOI body biasing capability, enabling overdrive mode that boosts core frequency
- **Robust** embedded nonvolatile memory (eNVM) qualified in automotive
- Unrivaed **immunity against radiation**, essential for harsh environments
- **Cost efficiency**
 - Highest digital & SRAM density of any planar technology
 - Smallest eNVM cell on the market (half the size vs 22 nm)
 - Lower structural cost than FinFET solutions

Resilient supply chain

Dual source with Samsung Foundry, Korea
and ST Crolles, France

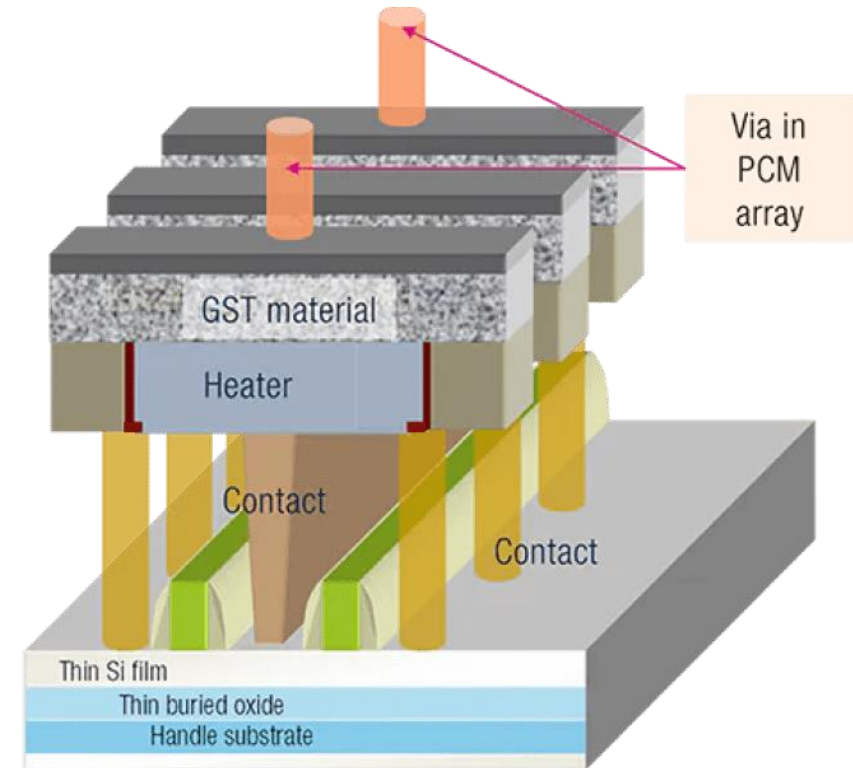
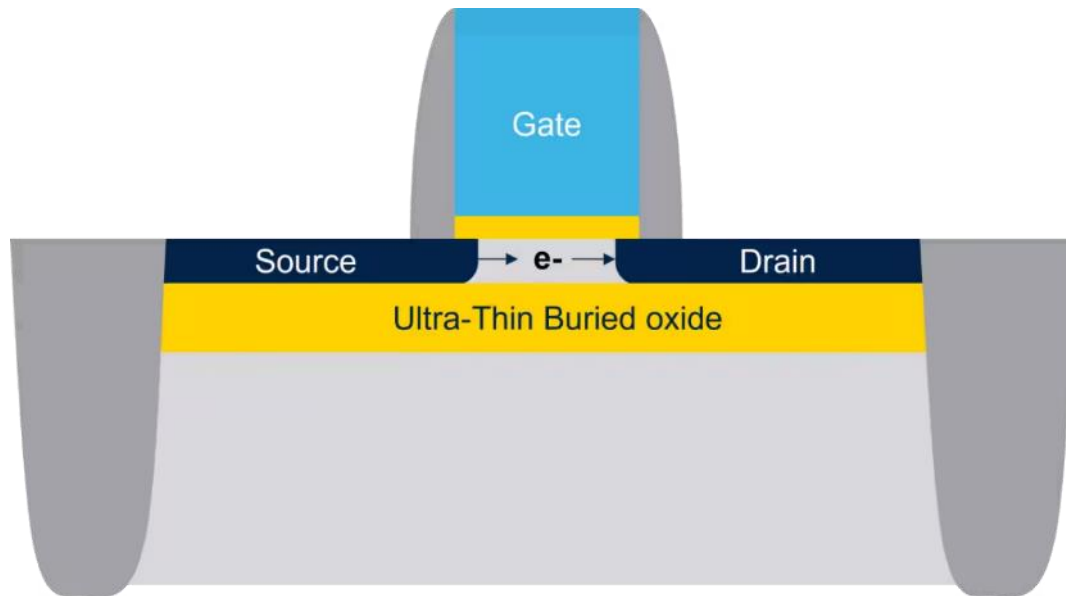


18 nm FD-SOI phase change memory (PCM) Technology breakthrough for MCUs

Fully depleted silicon on insulator
(FD-SOI)

+

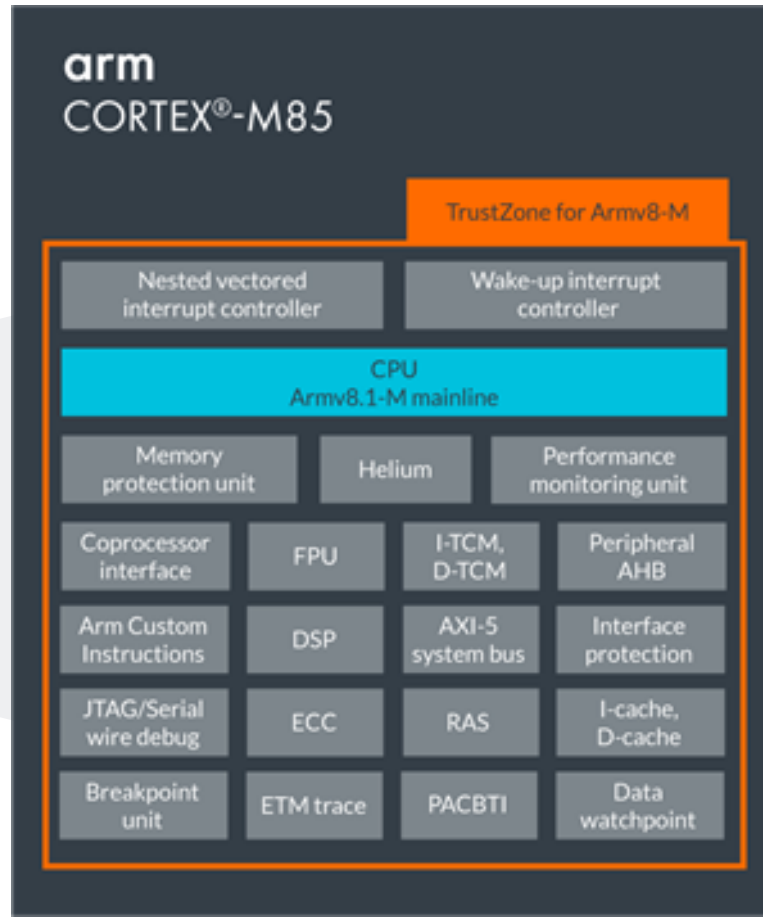
Embedded phase change memory
(ePCM)



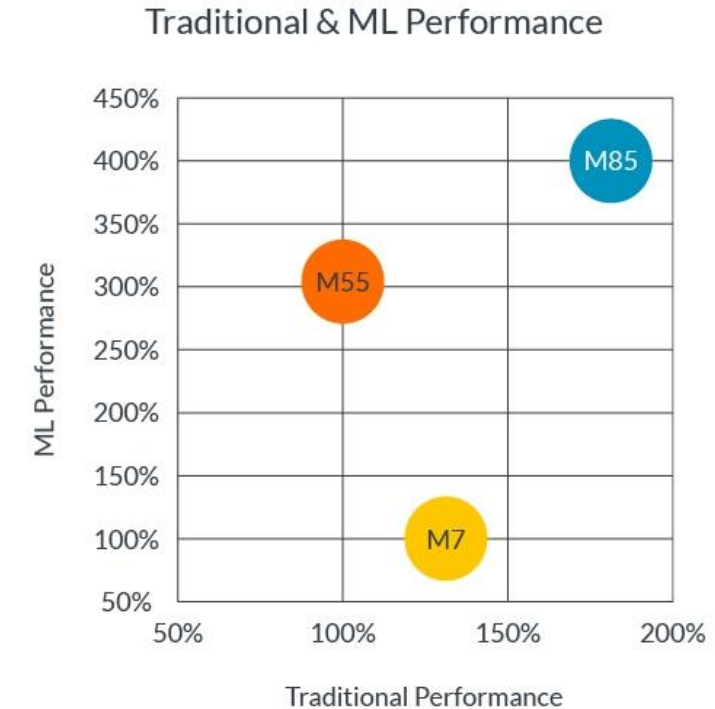
Cutting-edge product features



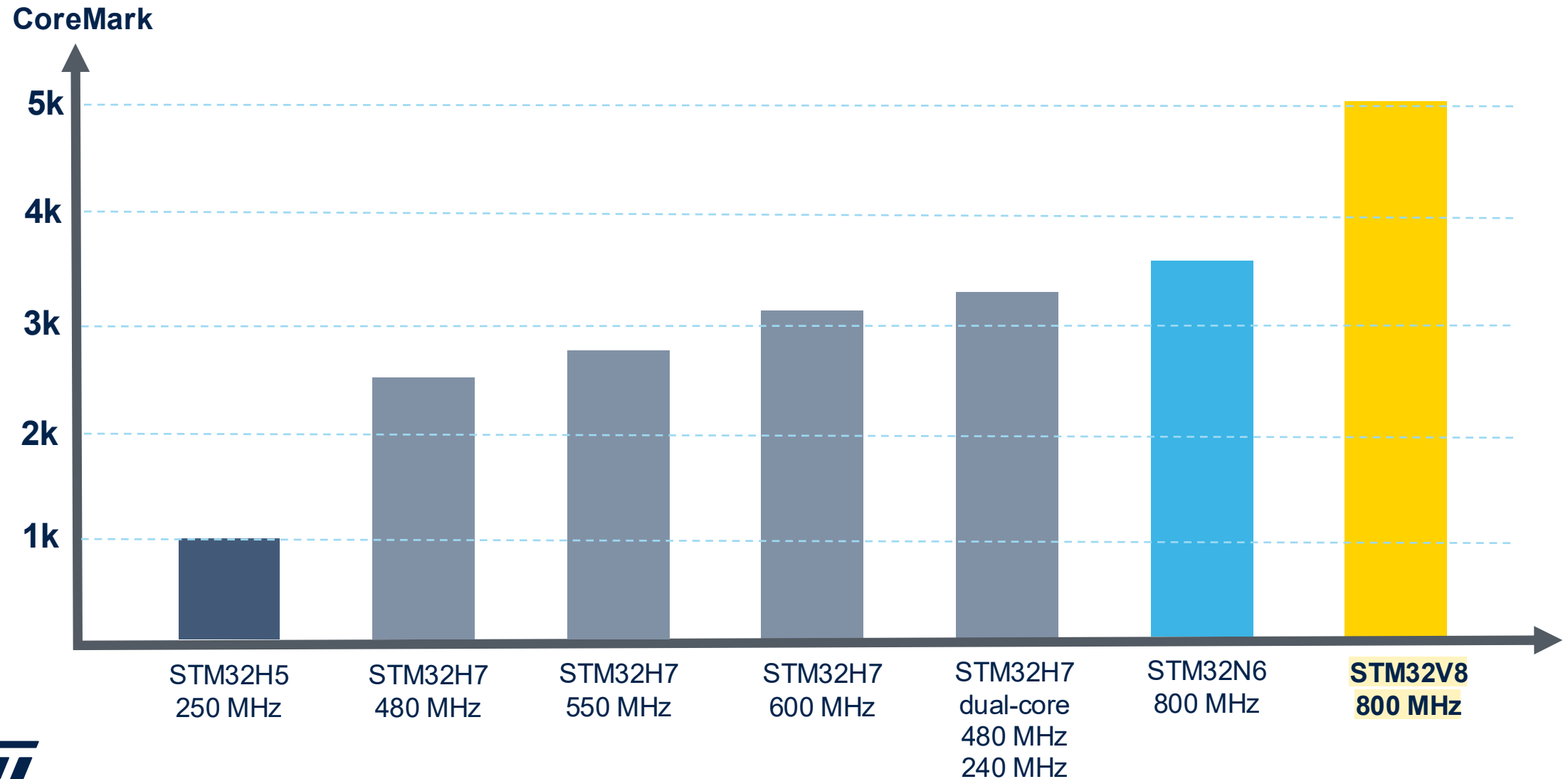
Arm Cortex[®]-M85: a cutting-edge MCU core



Up to 400% performance boost in DSP and ML workloads versus Cortex[®]-M7 core



Scalar performance increase



Edge AI demo: 6x more ML performance versus previous product generation

Set up

STM32Cube.AI

- YoloLC Model conversion
- Memory optimization
- Code optimization

STM32V8 discovery kit

- Cortex®-M85 up to 800 MHz
- Helium/MVE-enabled
- Model weights in eNVM
- Model buffering in SRAM

Frame
per second

STM32H7
480 MHz

x1

STM32V8
480 MHz

x3.5

STM32V8
800 MHz

x6



Arm Cortex®-M85 800 MHz DP-FPU, MPU, ETM TrustZone®, MVE 2x 32 KB – CACHE (I/D)	Embedded memories	Connectivity	Timers/Control
	Up to 4 MB embedded NVM 2x Banks 2 MB w./ ECC	1x Gbit Ethernet with TSN	3x motor control timers
	1.5 MB SYST.RAM w/ECC (partial)	3x FD-CAN	HR timer, 10x 16-bit timers
	2x 128 KB Data NVM	1x USB HS + 1x USB FS w/PHYs	5x 16-bit LP timers
	192 KB 0-WS TCM Up to 512 KB TCM w/ ECC	1x UCPD controller	4x 32-bit GP timers
	256 KB SYST NVM	3x I ² C + 2x I3C	2x watchdog timers, gtx timer
	8 KB Backup RAM	5x UART, 5x USART, 1x LPUART	FMAC + cordic
System GPDMA/HPDMA DEBUG GPIO SMPS, LDO (for RAM) RTC, backup, Reg	External memory interfaces	Graphics	Security
	hexa-SPI w/MCE	TFT LCD controller	Unique immutable ID
	octo-SPI w/MCE	Chrom-GRC	Secure storage (HUK)
	2x SD/SDIO/MMC	Chrom-ART Accelerator	Secure boot/Upgrade (STiRoT)
	Fast FMC w/MCE (SDRAM, NDR, NAND)	JPEG hardware accelerator	Secure debug
Analog Digital temperature sensor 3x 12-bit ADC, 1x 12-bit DAC	Audio	Camera	Crypto SAES/AES
	2x SAI, 4x I2S (SPI), SPDIFRX	16-bit parallel camera I/F	OTF XSPI Enc./ Dec
	1x MDF (6 filters) + ADF		Tampering services

STM32V8 brings both **scalar and vector performance** improvements that enable cutting-edge **digital signal processing** and machine learning, alongside **graphics capabilities** and next-level **security**.

Run efficient GUIs with high FPS & low CPU load

STM32 graphics IP

Chrom-ART

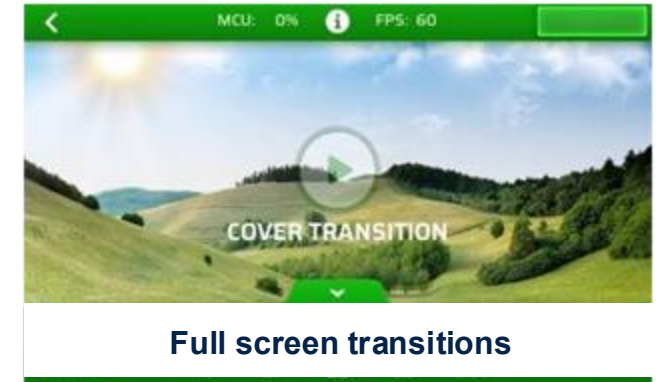
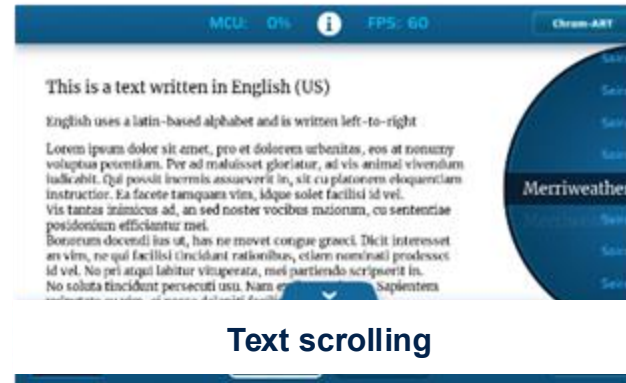
- Efficient 2D copy
- Alpha blending
 - For transparency effects
 - Anti-aliased bitmap fonts
- Color format conversion

JPEG codec

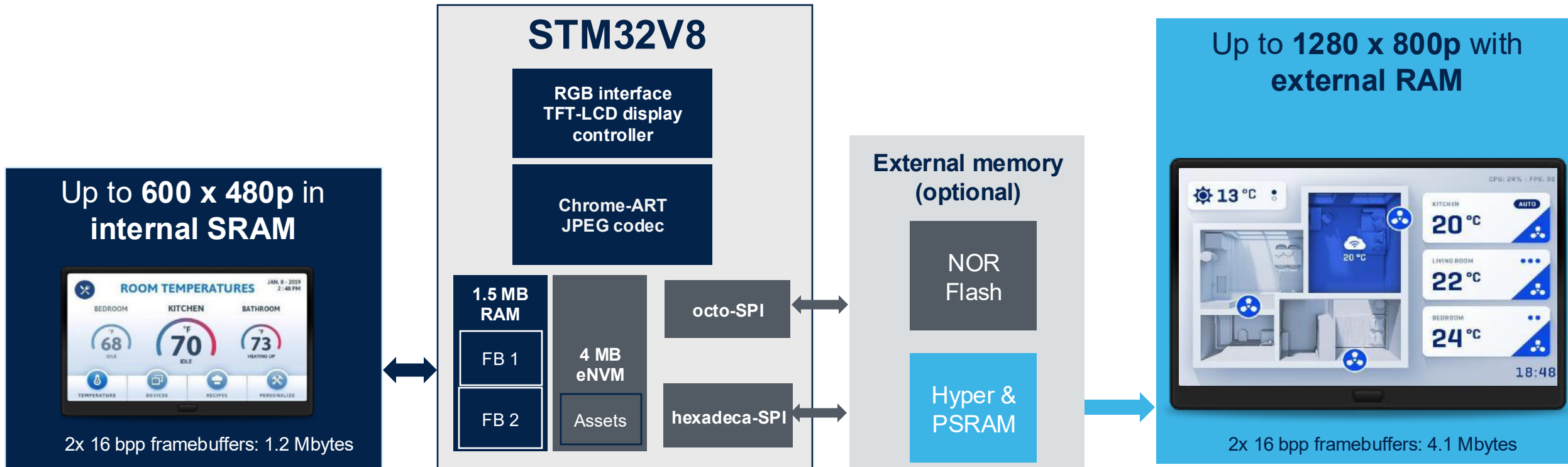
- JPEG compression & decompression
- Full & easy management of JPEG headers

LTDC/Display controller

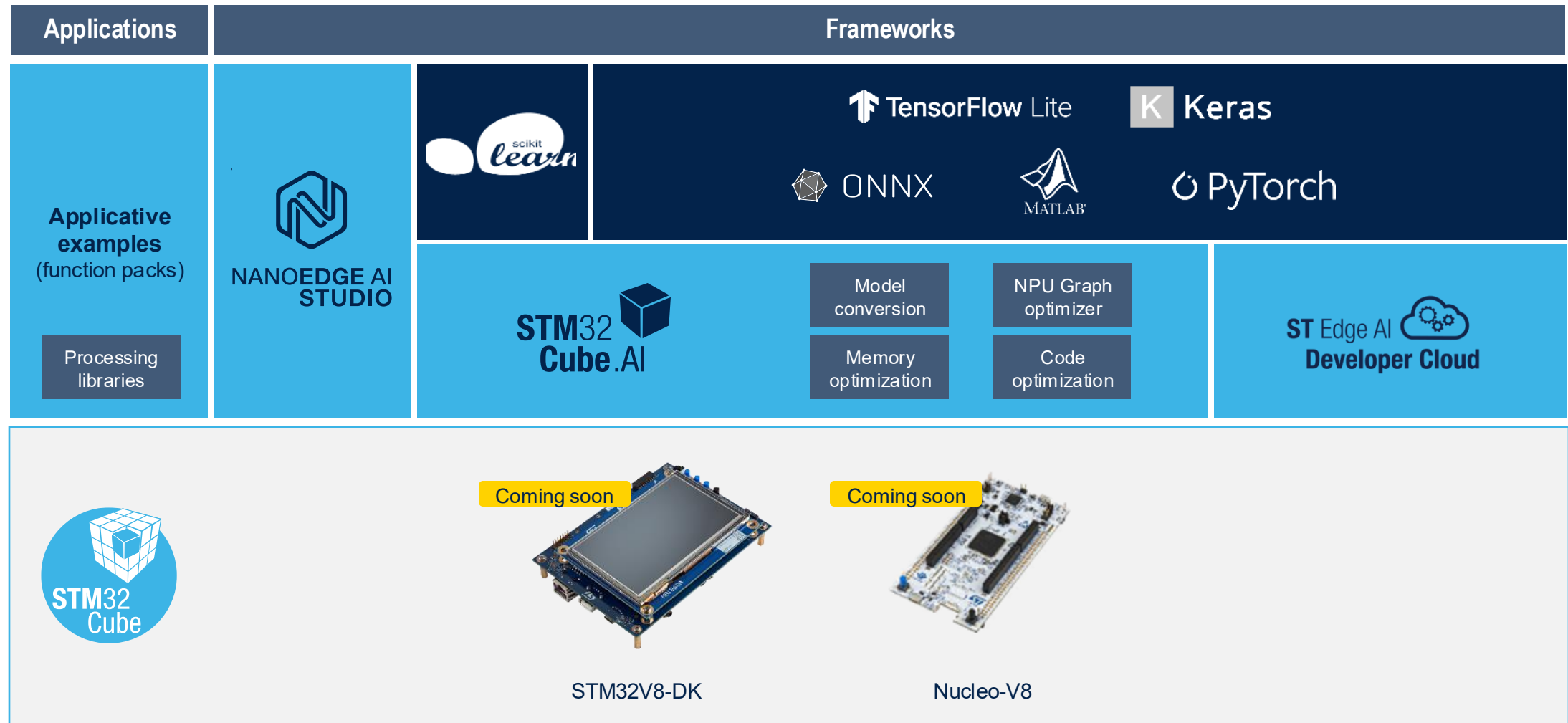
Efficient & automatic display updates



Advanced graphics with STM32V8

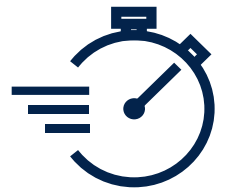


Supported by ST edge AI ecosystem leveraging Cortex®-M85 MVE accelerator

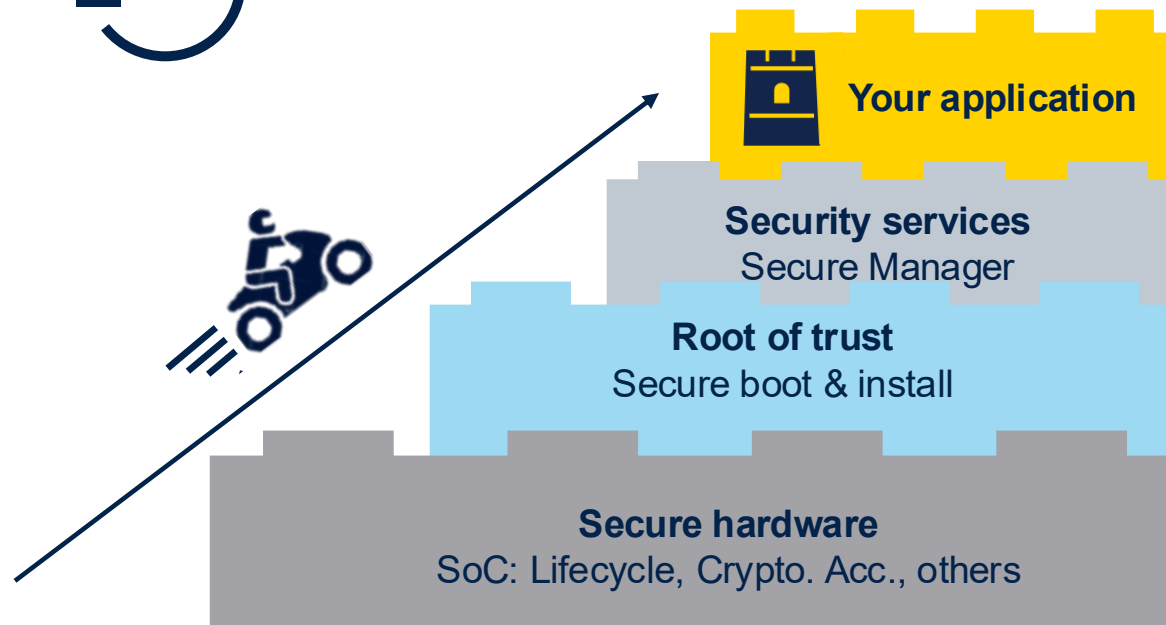


A scalable security offering

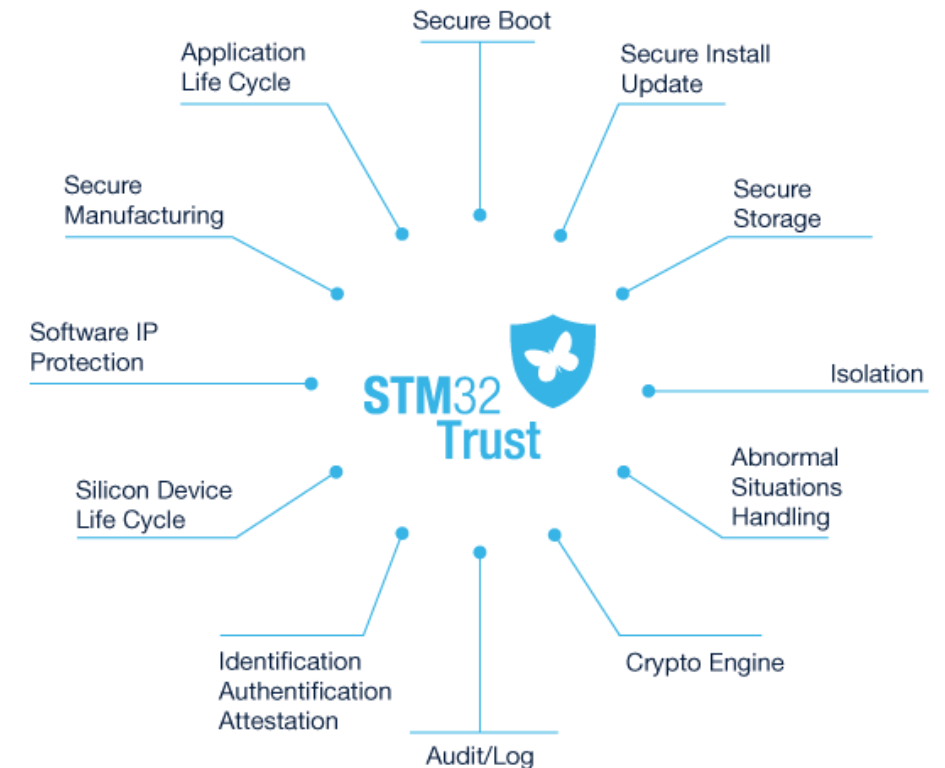
Choose your preferred security track, from secure hardware to the entire STM32Trust function coverage



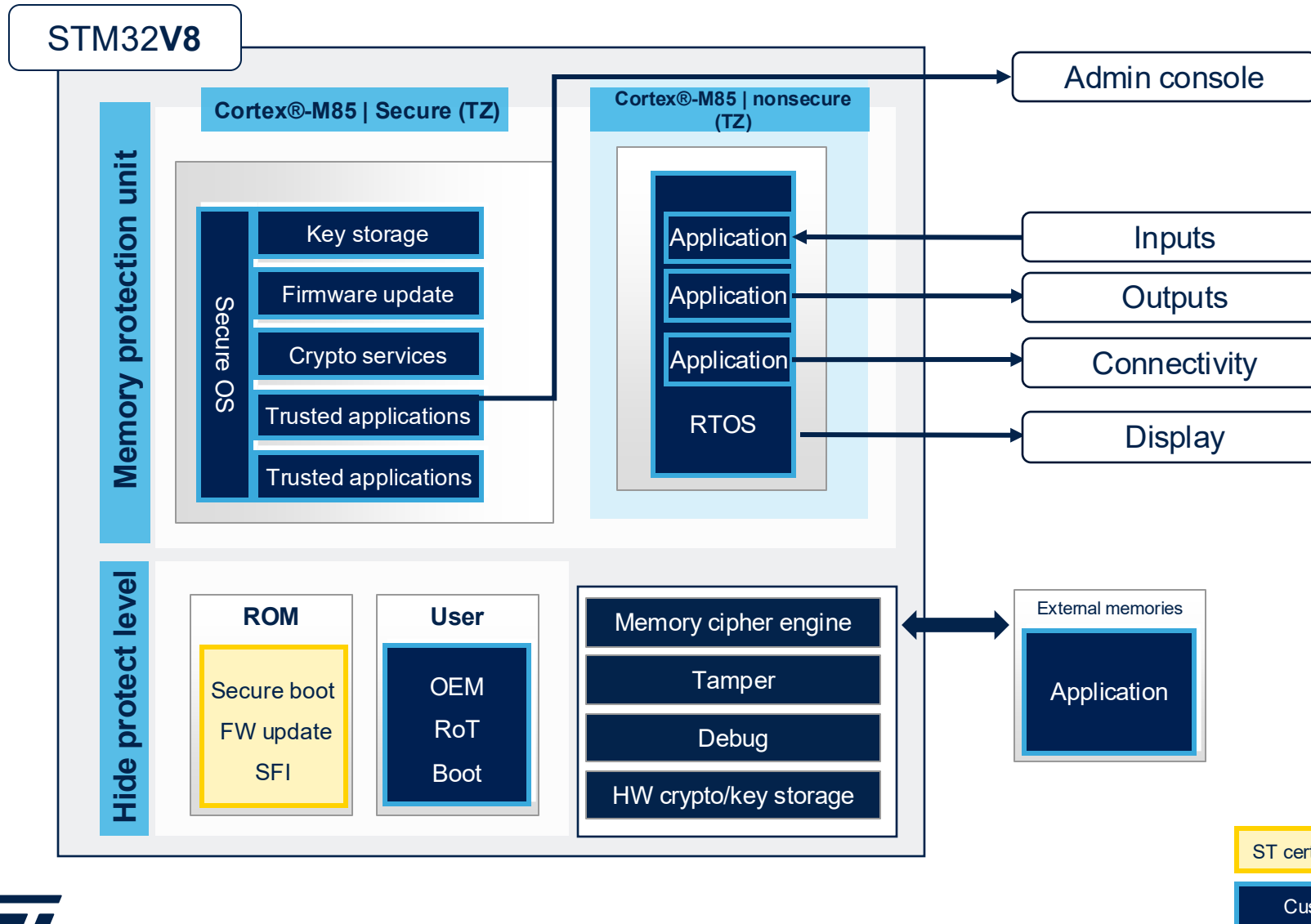
Innovate faster!



Target certifications



Strong security for regulatory compliance



**A robust security design
for handling large data
throughput**



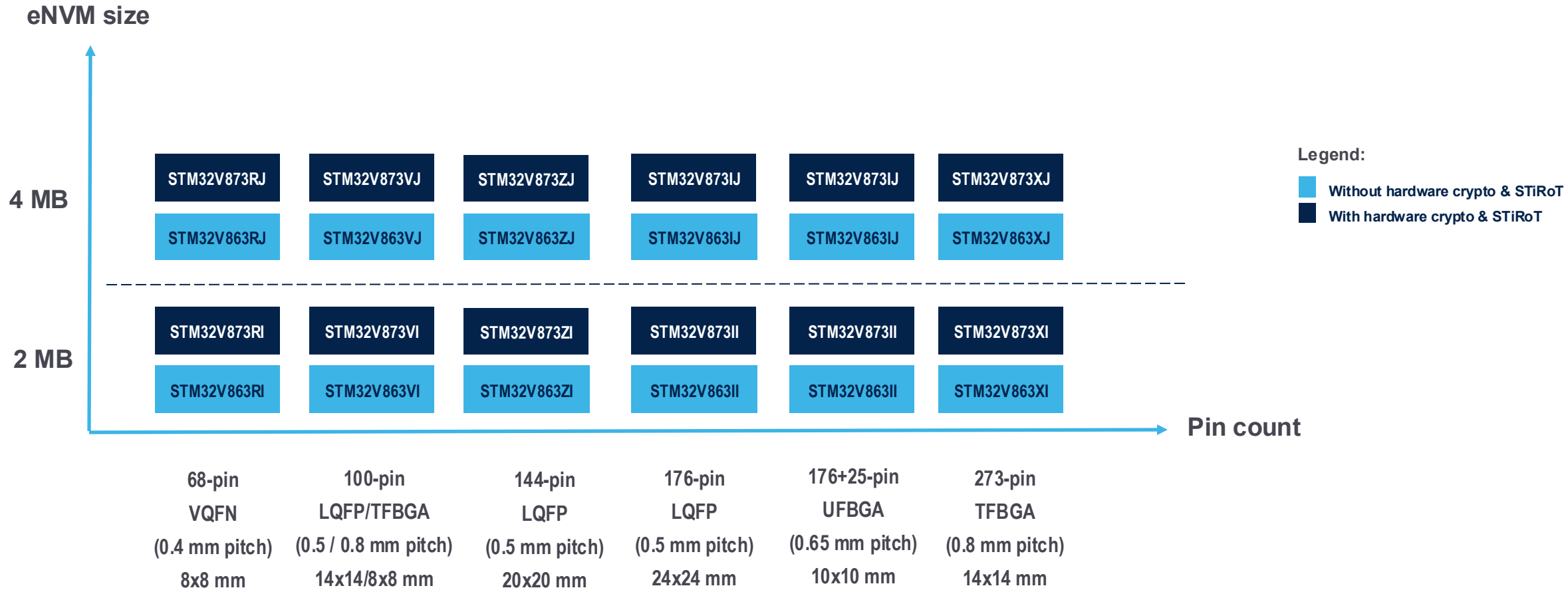
Target certifications

STM32V8 features

Overview compared with STM32N6 and STM32H7

	Computer vision edge AI	Industrial	
	High-performance MCU with NPU	High-performance MCUs	
	STM32N6	STM32H7	STM32V8
Computing performance	3,360 CoreMark Cortex®-M55 up to 800 MHz	Up to 3,347 CoreMark Cortex®-M7 up to 600 MHz Cortex®-M4 at 240 MHz	Up to 5,072 CoreMark Cortex®-M85 up to 800 MHz
Memory	External flash memory / 4.2 Mbytes RAM hexa-SPI, octo-SPI, FMC	Up to 2 Mbytes eNVM Up to 1.4 Mbytes RAM hexa-SPI, octo-SPI, FMC	Up to 4 Mbytes eNVM Up to 1.5 Mbytes RAM hexa-SPI, octo-SPI, FMC
Graphics	2.5D GPU – NeoChrom, Chrom-ART	2.5D GPU – NeoChrom, Chrom-ART	Chrom-ART
Edge AI	Neural-ART Accelerator (600 GOPS)	Software acceleration only	Software acceleration only leveraging Helium/MVE
Image processing	MIPI CSI-2 interface & ISP H.264 encoder	16-bit parallel camera I/F	16-bit parallel camera I/F
Security	Target SESIP3 & PSA L3 certifications	Up to target SESIP3 & PSA L3 certifications	Target SESIP3 & PSA L3 certifications
Robustness (Tj)	Up to 125°C	Up to 140°C	Up to 140°C PCM memory radiation immunity

Package line-up



Our technology starts with You



[Find out more in the tech dive](#)

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